

Final datasheet
CoolSiC™ 1400 V SiC MOSFET G2 : Silicon Carbide MOSFET with .XT interconnection technology

Features

- $V_{DS} = 1400\text{ V}$ at $T_{vj} = 25^{\circ}\text{C}$
- $I_{DC} = 53\text{ A}$ at $T_C = 100^{\circ}\text{C}$
- $R_{DS(on)} = 24\text{ m}\Omega$ at $V_{GS} = 18\text{ V}$, $T_{vj} = 25^{\circ}\text{C}$
- Very low switching losses
- Short circuit withstand time $2\text{ }\mu\text{s}$
- Benchmark gate threshold voltage, $V_{GS(th)} = 4.2\text{ V}$
- Robust against parasitic turn on, 0 V turn-off gate voltage can be applied
- Robust body diode for hard commutation
- .XT interconnection technology for best-in-class thermal performance
- Suitable Infineon gate drivers can be found under <https://www.infineon.com/gdfinder>

Potential applications

- General purpose drives (GPD)
- EV Charging
- Online UPS / Industrial UPS
- String inverter
- Energy storage systems (ESS)
- Welding

Product validation

- Qualified for industrial applications according to the relevant tests of JEDEC47/20/22

Description

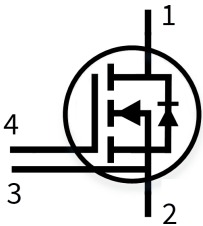
Pin definition:

- Pin 1 – Drain
- Pin 2 – Source
- Pin 3 – Kelvin sense contact
- Pin 4 – Gate

Note: the source and sense pins are not exchangeable, their exchange might lead to malfunction



- Halogen-free
- Green
- Lead-free
- RoHS



Type	Package	Marking
IMZC140R024M2H	PG-TO247-4-U07	14M2H024



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1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}	Wave soldering only allowed at leads 1.6 mm (0.063 in.) from case for 10 s			260	°C
Mounting torque	M	M3 screw, Maximum of mounting processes: 3			0.6	Nm
Thermal resistance, junction-ambient	$R_{th(j-a)}$				62	K/W
MOSFET/body diode thermal resistance, junction-case	$R_{th(j-c)}$			0.35	0.46	K/W

2 MOSFET

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25\text{ °C}$		1400	V
Continuous DC drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{DDC}	$V_{GS} = 18\text{ V}$	$T_c = 25\text{ °C}$	74	A
			$T_c = 100\text{ °C}$	53	
Peak drain current, t_p limited by $T_{vj(max)}$ ¹⁾	I_{DM}	$V_{GS} = 18\text{ V}$		265	A
Gate-source voltage, max. transient voltage	V_{GS}	$t_p \leq 0.5\text{ }\mu\text{s}$, $D < 0.01$		-10...25	V
Gate-source voltage, max. static voltage ²⁾	V_{GS}			-7...23	V
Avalanche energy, single pulse	E_{AS}	$I_D = 32.1\text{ A}$, $V_{DD} = 50\text{ V}$, $L = 0.8\text{ mH}$, $T_{vj(start)} = 25\text{ °C}$		401	mJ
Avalanche energy, repetitive	E_{AR}	$I_D = 32.1\text{ A}$, $V_{DD} = 50\text{ V}$, $L = 3.9\text{ }\mu\text{H}$, $T_{vj(start)} = 25\text{ °C}$		2	mJ
Short-circuit withstand time	t_{SC}	$V_{DD} \leq 800\text{ V}$, $V_{DS,peak} < 1400\text{ V}$, $V_{GS(on)} = 15\text{ V}$, $T_{vj(start)} = 25\text{ °C}$		2	μs
Power dissipation, limited by $T_{vj(max)}$	P_{tot}		$T_c = 25\text{ °C}$	330	W
			$T_c = 100\text{ °C}$	160	

1) Verified by design.

2) The maximum gate-source voltage in the application design should be in accordance to IPC-9592B.

Table 3 Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{GS(on)}$		15...18	V
Recommended turn-off gate voltage	$V_{GS(off)}$		-5...0	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 32.1\text{ A}$		$T_{vj} = 25\text{ °C}$, $V_{GS(on)} = 18\text{ V}$	24	mΩ
				$T_{vj} = 150\text{ °C}$, $V_{GS(on)} = 18\text{ V}$	51.6	
				$T_{vj} = 175\text{ °C}$, $V_{GS(on)} = 18\text{ V}$	60	
				$T_{vj} = 25\text{ °C}$, $V_{GS(on)} = 15\text{ V}$	30	
Gate-source threshold voltage	$V_{GS(th)}$	$I_D = 10.1\text{ mA}$, $V_{DS} = V_{GS}$ (tested after 1 ms pulse at $V_{GS} = 20\text{ V}$)	3.5	$T_{vj} = 25\text{ °C}$	4.2	V
				$T_{vj} = 175\text{ °C}$	3.2	
Zero gate-voltage drain current	I_{DSS}	$V_{DS} = 1400\text{ V}$, $V_{GS} = 0\text{ V}$		$T_{vj} = 25\text{ °C}$	240	μA
				$T_{vj} = 175\text{ °C}$	4.1	
Gate leakage current	I_{GSS}	$V_{DS} = 0\text{ V}$		$V_{GS} = 23\text{ V}$	120	nA
				$V_{GS} = -10\text{ V}$	-120	
Forward transconductance	g_{fs}	$I_D = 32.1\text{ A}$, $V_{DS} = 20\text{ V}$		21		S
Internal gate resistance	$R_{G,int}$	$f = 1\text{ MHz}$, $V_{AC} = 25\text{ mV}$		2.5		Ω
Input capacitance	C_{iss}	$V_{DS} = 1000\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$		2290		pF
Output capacitance	C_{oss}	$V_{DS} = 1000\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$		78		pF
Reverse transfer capacitance	C_{rss}	$V_{DS} = 1000\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 100\text{ kHz}$, $V_{AC} = 25\text{ mV}$		7		pF
C_{oss} stored energy	E_{oss}	Calculated based on $C_{oss} = f(V_{DD})$		50		μJ
Output charge	Q_{oss}	Calculated based on $C_{oss} = f(V_{DD})$		137		nC
Effective output capacitance, energy related	$C_{o(er)}$	$V_{DS} = 0...1000\text{ V}$, $V_{GS} = 0\text{ V}$, Calculated based on E_{oss}		156		pF
Effective output capacitance, time related	$C_{o(tr)}$	$I_D = \text{constant}$, $V_{DS} = 0...1000\text{ V}$, $V_{GS} = 0\text{ V}$, Calculated based on Q_{oss}		171		pF

(table continues...)

Table 4 (continued) **Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_G	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, turn-on pulse		62		nC
Plateau gate charge	$Q_{GS(pl)}$	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, turn-on pulse		17.4		nC
Gate-drain charge	Q_{GD}	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, turn-on pulse		16.2		nC
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	7.8		ns
			$T_{vj} = 175 \text{ °C}$	6.8		
Rise time	t_r	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	4.6		ns
			$T_{vj} = 175 \text{ °C}$	4.3		
Turn-off delay time	$t_{d(off)}$	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	19		ns
			$T_{vj} = 175 \text{ °C}$	21		
Fall time	t_f	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	7.6		ns
			$T_{vj} = 175 \text{ °C}$	8.3		
Turn-on energy	E_{on}	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	288		μJ
			$T_{vj} = 175 \text{ °C}$	888		
Turn-off energy	E_{off}	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	121		μJ
			$T_{vj} = 175 \text{ °C}$	140		
Total switching energy ¹⁾	E_{tot}	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = 0/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	482		μJ
			$T_{vj} = 175 \text{ °C}$	1332		

(table continues...)

3 Body diode (MOSFET)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-on energy at -5 V	E_{on}	$V_{DD} = 1000 \text{ V}$, $I_D = 32.1 \text{ A}$, $V_{GS} = -5/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = -5 \text{ V}$	$T_{vj} = 25 \text{ °C}$	288		μJ
			$T_{vj} = 175 \text{ °C}$	912		
Turn-off energy at -5 V	E_{off}	$V_{DD} = 1000 \text{ V}$, $V_{GS} = -5/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = -5 \text{ V}$	$T_{vj} = 25 \text{ °C}$	55		μJ
			$T_{vj} = 175 \text{ °C}$	65		
Total switching energy at -5 V ¹⁾	E_{tot}	$V_{DD} = 1000 \text{ V}$, $V_{GS} = -5/18 \text{ V}$, $R_{G,ext} = 2.3 \Omega$, $L_\sigma = 12 \text{ nH}$, diode: body diode at $V_{GS} = -5 \text{ V}$	$T_{vj} = 25 \text{ °C}$	416		μJ
			$T_{vj} = 175 \text{ °C}$	1290		
Virtual junction temperature	T_{vj}		-55		175	$^{\circ}\text{C}$

1) including E_{fr}

Note: The chip technology was characterized up to 200 kV/ μs . The measured dV/dt was limited by measurement test setup and package.

Characteristics at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified.

3 Body diode (MOSFET)

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage	V_{DSS}	$T_{vj} \geq 25 \text{ °C}$		1400	V
Continuous reverse drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$	I_{SDC}	$V_{GS} = 0 \text{ V}$	$T_c = 25 \text{ °C}$	60	A
			$T_c = 100 \text{ °C}$	33	
Peak reverse drain current, t_p limited by $T_{vj(max)}$	I_{SM}	$V_{GS} = 0 \text{ V}$		159	A

Table 6 **Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Drain-source reverse voltage	V_{SD}	$I_{SD} = 32.1 \text{ A}$, $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$	4.2	5.5	V
			$T_{vj} = 100 \text{ °C}$	4.11		
			$T_{vj} = 175 \text{ °C}$	4.05		
MOSFET forward recovery charge	Q_{fr}	$V_{DD} = 1000 \text{ V}$, $I_{SD} = 32.1 \text{ A}$, $V_{GS} = 0 \text{ V}$, $R_{GS(on)} = 2.3 \text{ } \Omega$, Q_{fr} includes also Q_C	$T_{vj} = 25 \text{ °C}$	0.34		μC
			$T_{vj} = 175 \text{ °C}$	1.06		
MOSFET peak forward recovery current	I_{frm}	$V_{DD} = 1000 \text{ V}$, $I_{SD} = 32.1 \text{ A}$, $V_{GS} = 0 \text{ V}$, $R_{GS(on)} = 2.3 \text{ } \Omega$, Q_{fr} includes also Q_C	$T_{vj} = 25 \text{ °C}$	59		A
			$T_{vj} = 175 \text{ °C}$	116		
MOSFET forward recovery energy	E_{fr}	$V_{DD} = 1000 \text{ V}$, $I_{SD} = 32.1 \text{ A}$, $V_{GS} = 0 \text{ V}$, $R_{GS(on)} = 2.3 \text{ } \Omega$, Q_{fr} includes also Q_C	$T_{vj} = 25 \text{ °C}$	73		μJ
			$T_{vj} = 175 \text{ °C}$	304		
MOSFET forward recovery energy at -5 V ¹⁾	E_{fr}	$V_{DD} = 1000 \text{ V}$, $I_{SD} = 32.1 \text{ A}$, $V_{GS} = -5 \text{ V}$, $R_{GS(on)} = 2.3 \text{ } \Omega$, Q_{fr} includes also Q_C	$T_{vj} = 25 \text{ °C}$	73		μJ
			$T_{vj} = 175 \text{ °C}$	313		
Virtual junction temperature	T_{vj}		-55		175	$^{\circ}\text{C}$

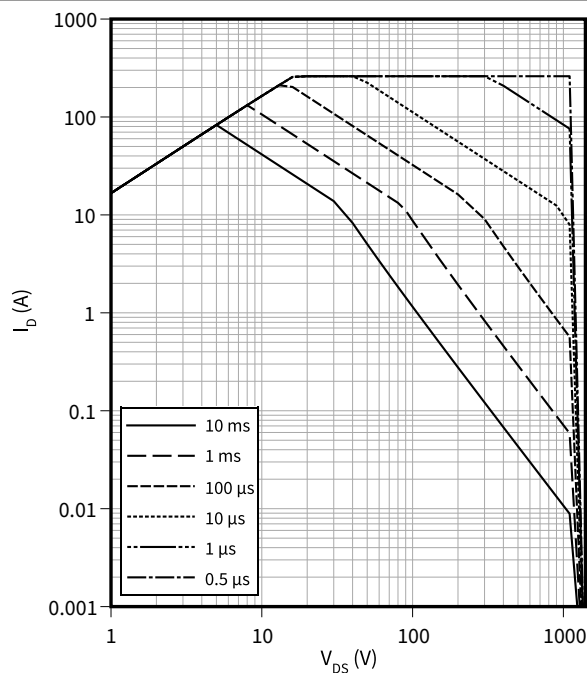
1) including E_{fr}

4 Characteristics diagrams

Safe operating area (SOA)

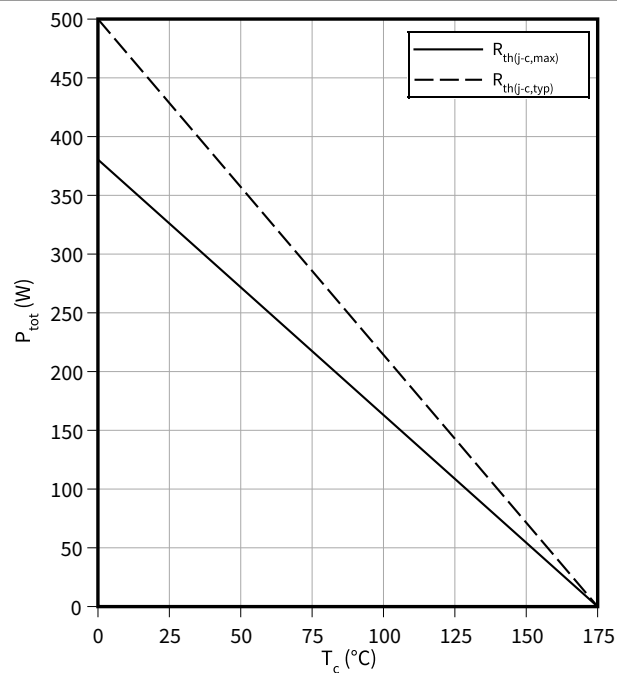
$$I_D = f(V_{DS})$$

$$T_{vj} \leq 175^\circ\text{C}, T_c = 25^\circ\text{C}$$



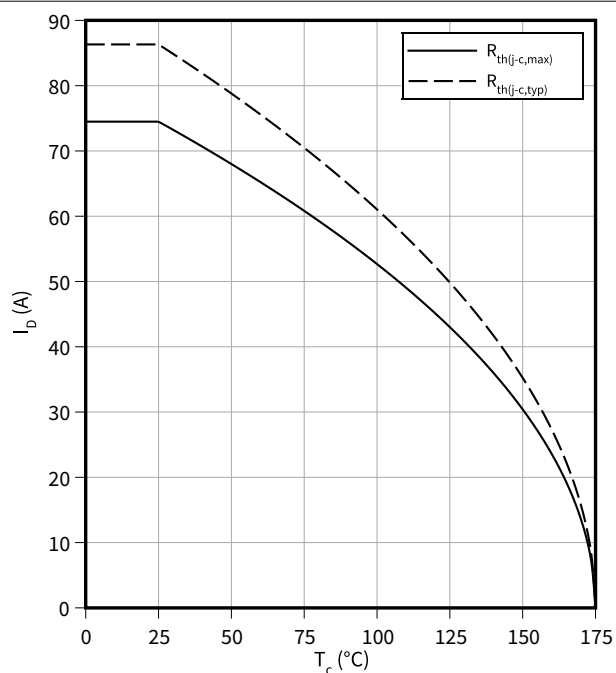
Power dissipation as a function of case temperature

$$P_{tot} = f(T_c)$$



Maximum DC drain to source current as a function of case temperature limited by bond wire

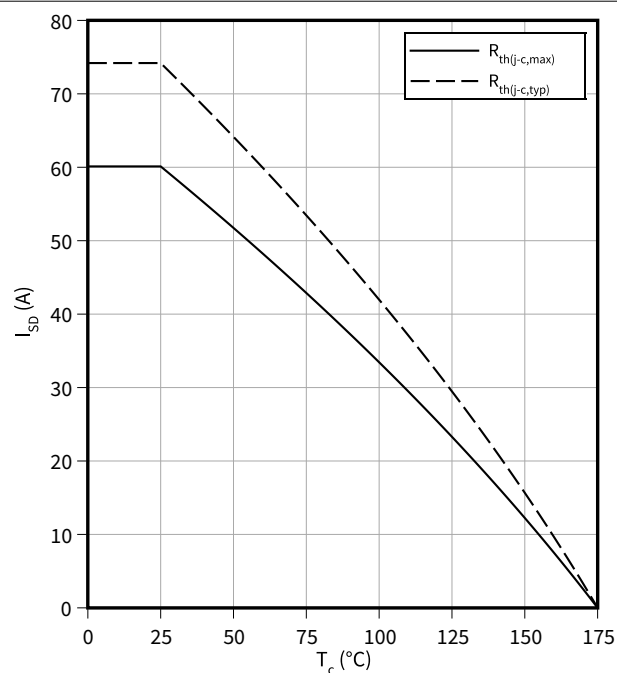
$$I_D = f(T_c)$$



Maximum source to drain current as a function of case temperature limited by bond wire

$$I_{SD} = f(T_c)$$

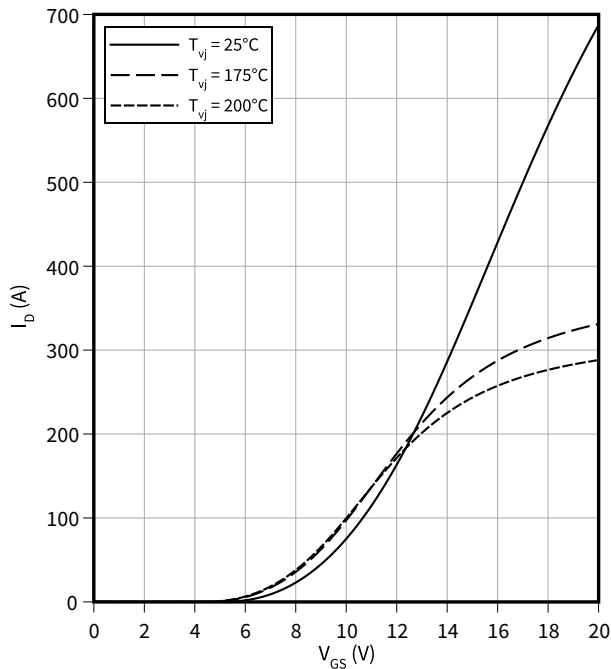
$$V_{GS} = 0\text{ V}$$



4 Characteristics diagrams

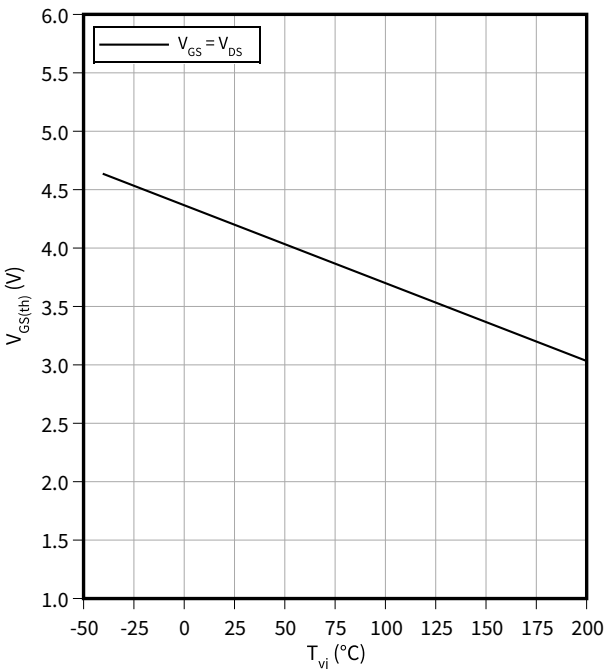
Typical transfer characteristic

$I_D = f(V_{GS})$
 $V_{DS} = 20\text{ V}$, $t_p = 20\text{ }\mu\text{s}$



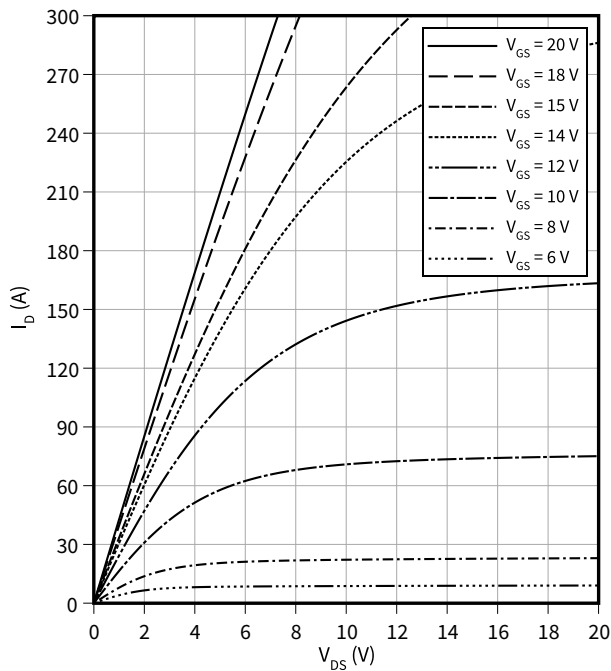
Typical gate-source threshold voltage as a function of junction temperature

$V_{GS(th)} = f(T_{vj})$
 $I_D = 10.1\text{ mA}$



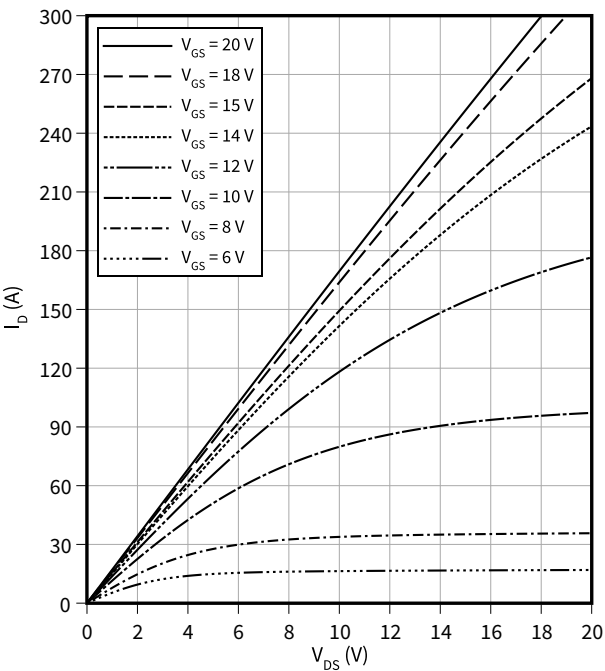
Typical output characteristic, V_{GS} as a parameter

$I_D = f(V_{DS})$
 $T_{vj} = 25\text{ }^\circ\text{C}$, $t_p = 20\text{ }\mu\text{s}$



Typical output characteristic, V_{GS} as a parameter

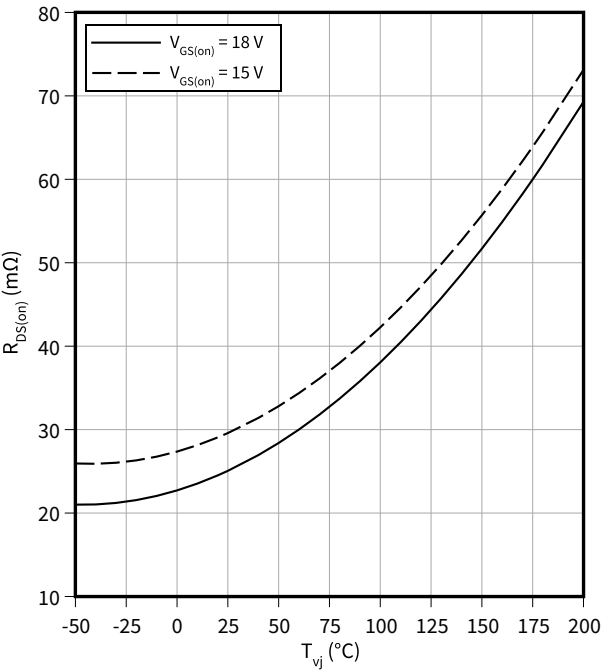
$I_D = f(V_{DS})$
 $T_{vj} = 175\text{ }^\circ\text{C}$, $t_p = 20\text{ }\mu\text{s}$



4 Characteristics diagrams

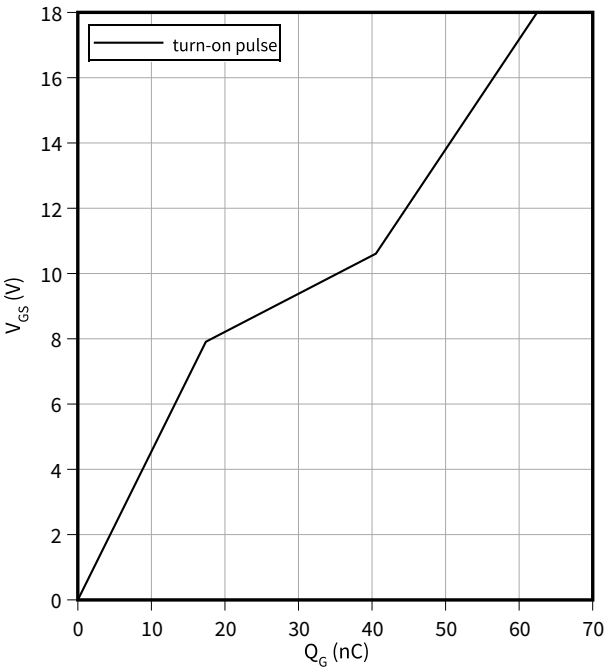
Typical on-state resistance as a function of junction temperature

$R_{DS(on)} = f(T_{vj})$
 $I_D = 32.1\text{ A}$



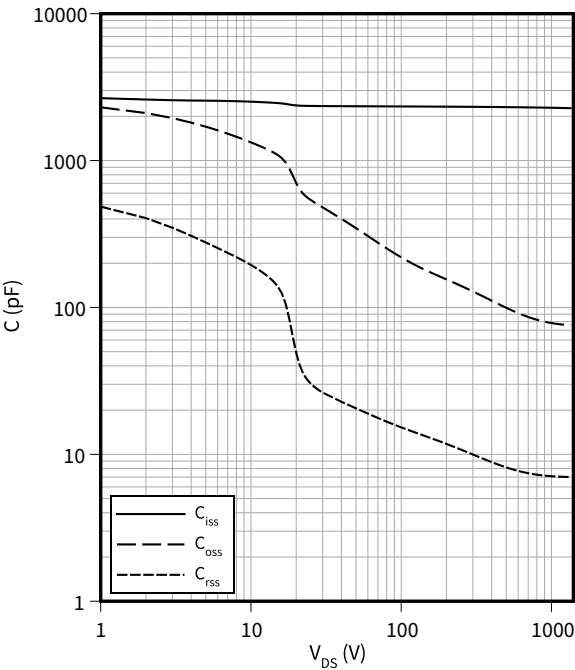
Typical gate charge

$V_{GS} = f(Q_G)$
 $I_D = 32.1\text{ A}, V_{DS} = 1000\text{ V}$



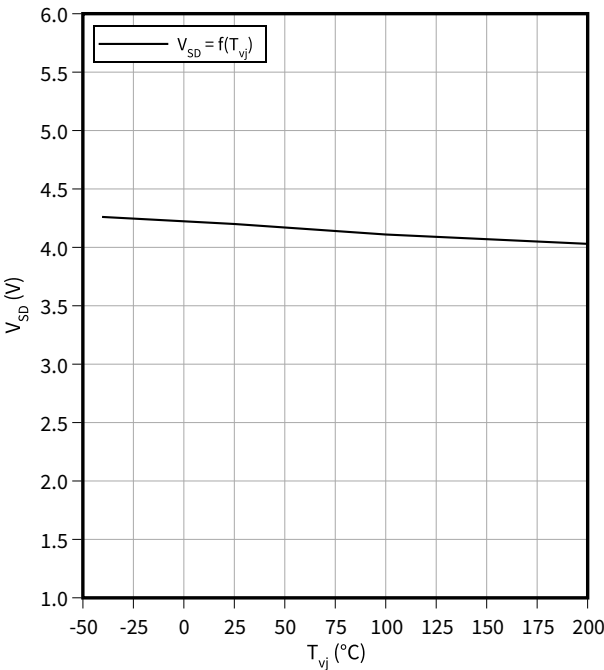
Typical capacitance as a function of drain-source voltage

$C = f(V_{DS})$
 $f = 100\text{ kHz}, V_{GS} = 0\text{ V}$



Typical reverse drain voltage as a function of junction temperature

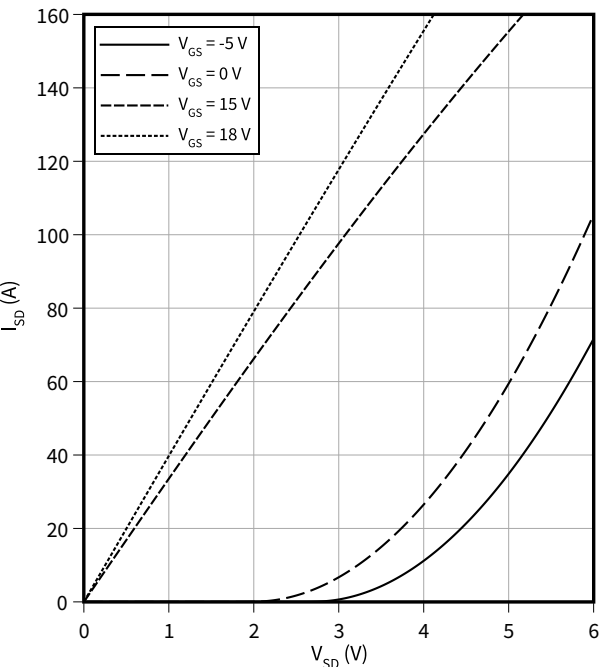
$V_{SD} = f(T_{vj})$
 $I_{SD} = 32.1\text{ A}, V_{GS} = 0\text{ V}$



4 Characteristics diagrams

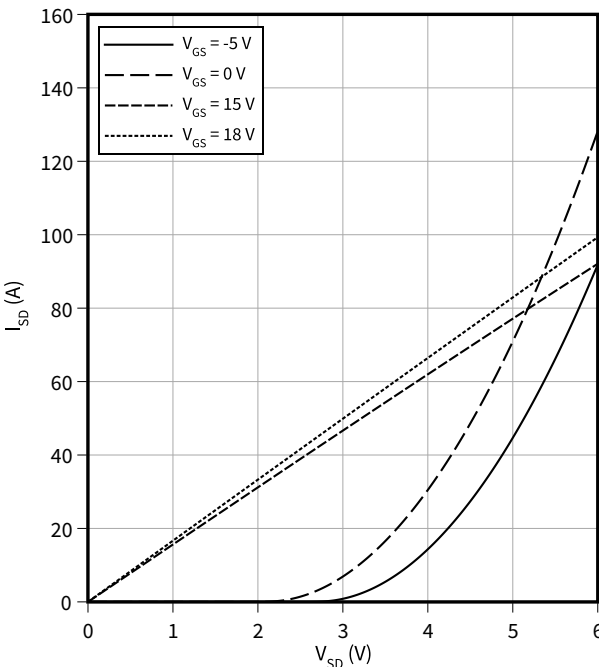
Typical reverse drain current as a function of reverse drain voltage, V_{GS} as a parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 25\text{ }^{\circ}\text{C}$, $t_p = 20\text{ }\mu\text{s}$



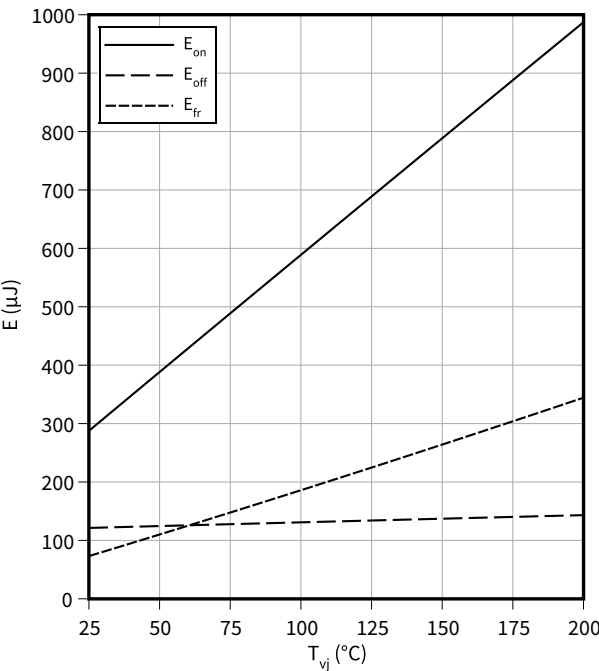
Typical reverse drain current as a function of reverse drain voltage, V_{GS} as a parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 175\text{ }^{\circ}\text{C}$, $t_p = 20\text{ }\mu\text{s}$



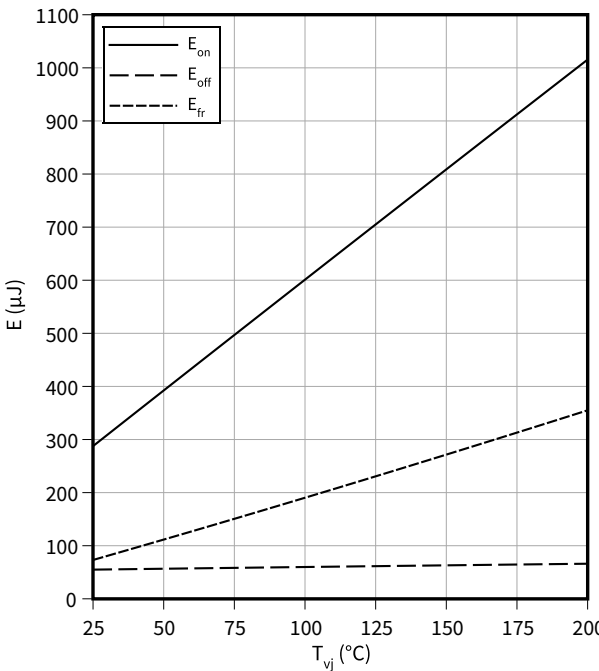
Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(T_{vj})$
 $V_{GS} = 0/18\text{ V}$, $I_D = 32.1\text{ A}$, $R_{G,ext} = 2.3\text{ }\Omega$, $V_{DD} = 1000\text{ V}$



Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5\text{ V}$

$E = f(T_{vj})$
 $V_{GS} = -5/18\text{ V}$, $I_D = 32.1\text{ A}$, $R_{G,ext} = 2.3\text{ }\Omega$, $V_{DD} = 1000\text{ V}$

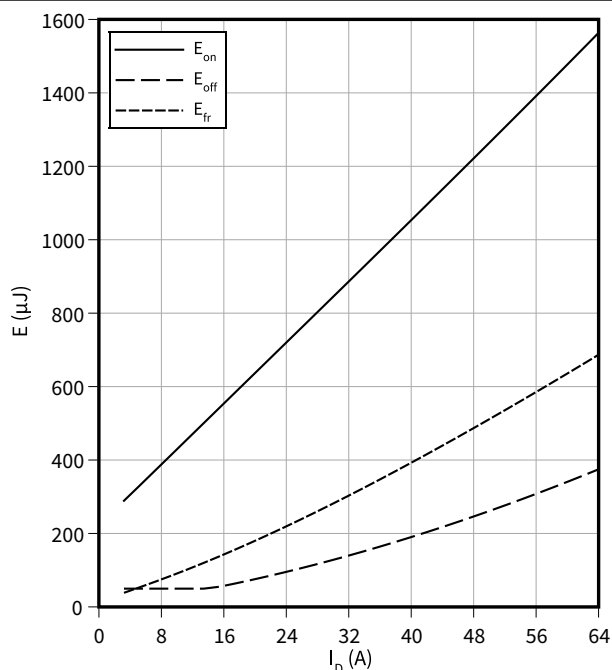


4 Characteristics diagrams

Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$E = f(I_D)$$

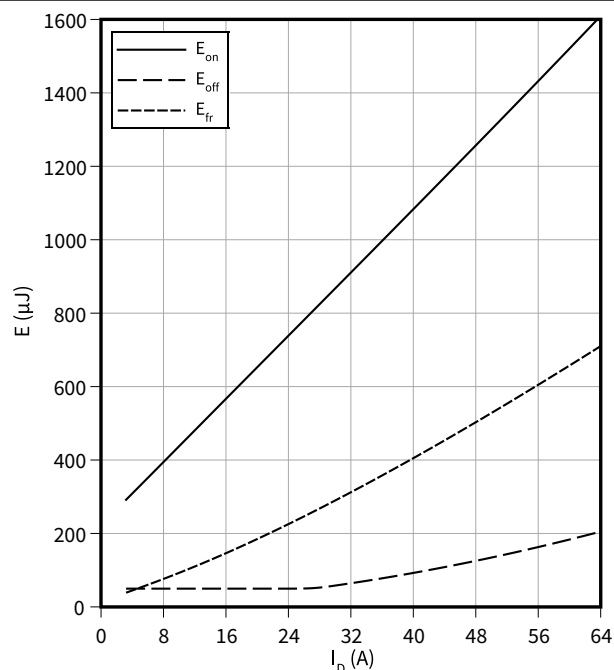
$V_{GS} = 0/18$ V, $T_{vj} = 175$ °C, $R_{G,ext} = 2.3$ Ω , $V_{DD} = 1000$ V



Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5$ V

$$E = f(I_D)$$

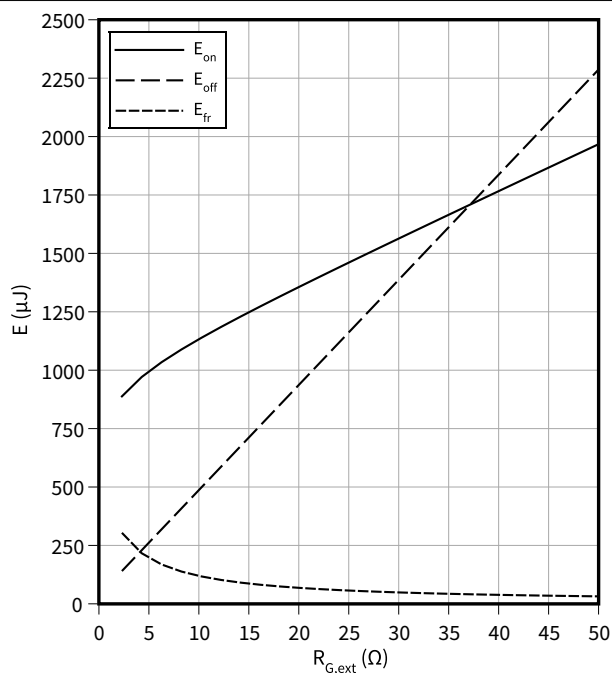
$V_{GS} = -5/18$ V, $T_{vj} = 175$ °C, $R_{G,ext} = 2.3$ Ω , $V_{DD} = 1000$ V



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$E = f(R_{G,ext})$$

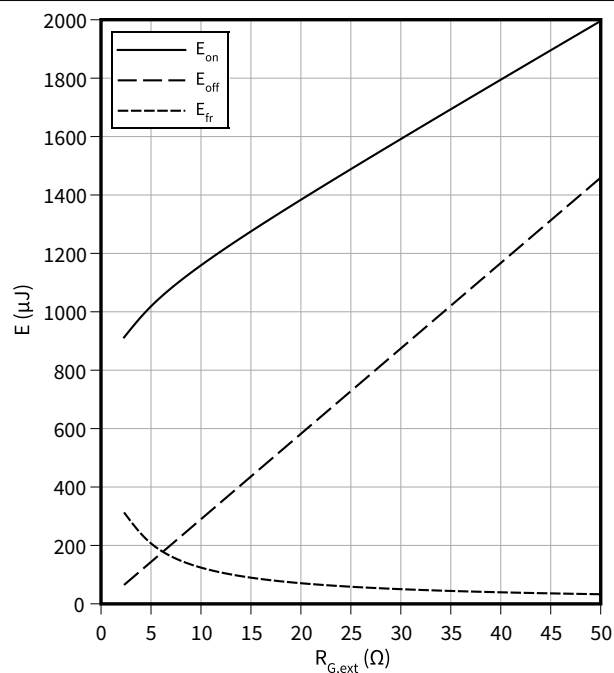
$V_{GS} = 0/18$ V, $I_D = 32.1$ A, $T_{vj} = 175$ °C, $V_{DD} = 1000$ V



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5$ V

$$E = f(R_{G,ext})$$

$V_{GS} = -5/18$ V, $I_D = 32.1$ A, $T_{vj} = 175$ °C, $V_{DD} = 1000$ V

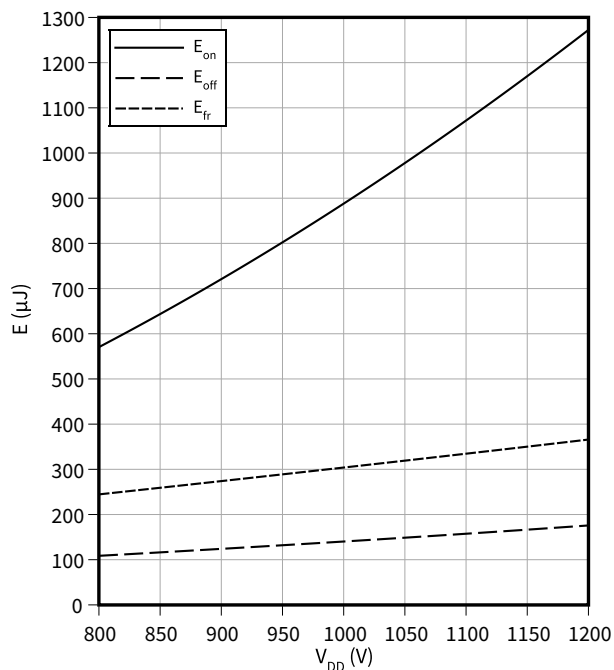


4 Characteristics diagrams

Typical switching energy as a function of DC link voltage, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$E = f(V_{DD})$$

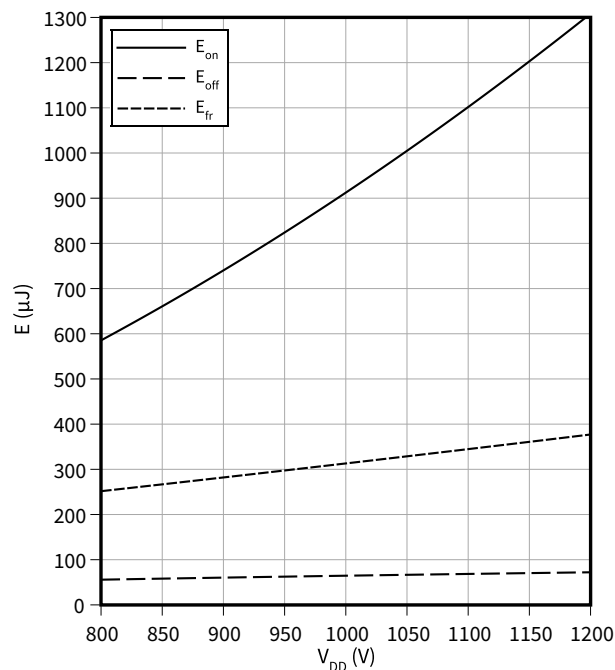
$V_{GS} = 0/18$ V, $I_D = 32.1$ A, $T_{vj} = 175$ °C, $R_{G,ext} = 2.3$ Ω



Typical switching energy as a function of DC link voltage, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = -5$ V

$$E = f(V_{DD})$$

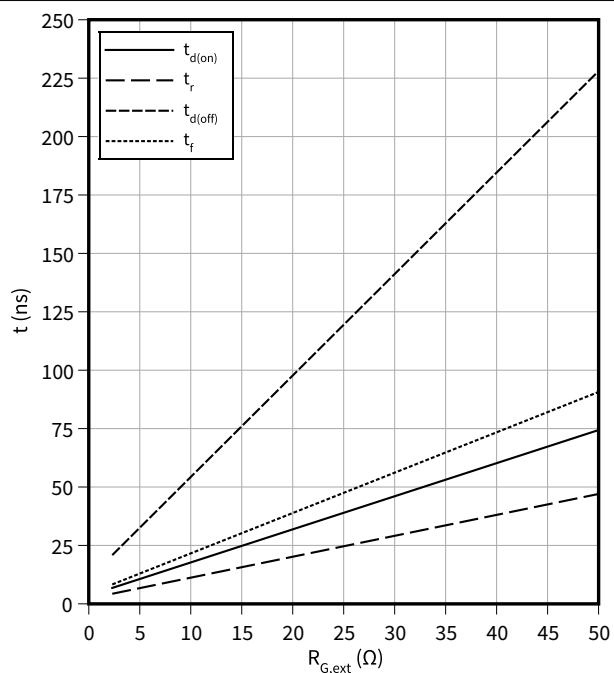
$V_{GS} = -5/18$ V, $I_D = 32.1$ A, $T_{vj} = 175$ °C, $R_{G,ext} = 2.3$ Ω



Typical switching times as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$t = f(R_{G,ext})$$

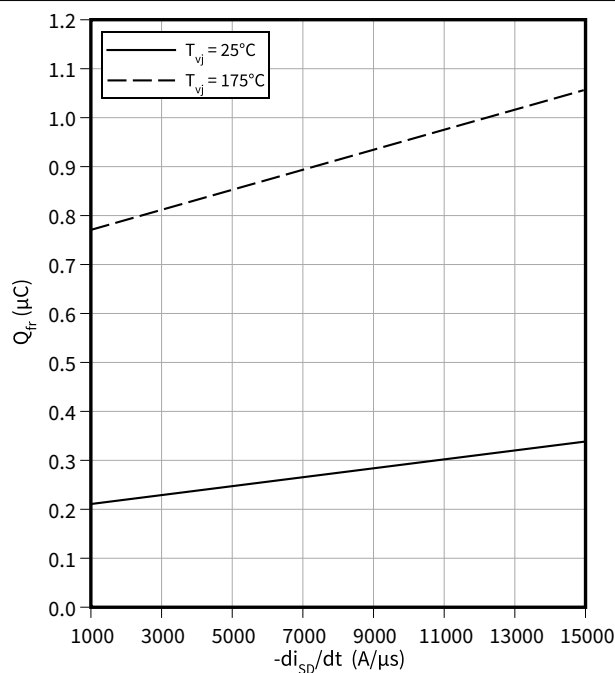
$V_{GS} = 0/18$ V, $I_D = 32.1$ A, $T_{vj} = 175$ °C, $V_{DD} = 1000$ V



Typical reverse recovery charge as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$Q_{fr} = f(-di_{SD}/dt)$$

$V_{GS} = 0/18$ V, $I_{SD} = 32.1$ A, $V_{DD} = 1000$ V



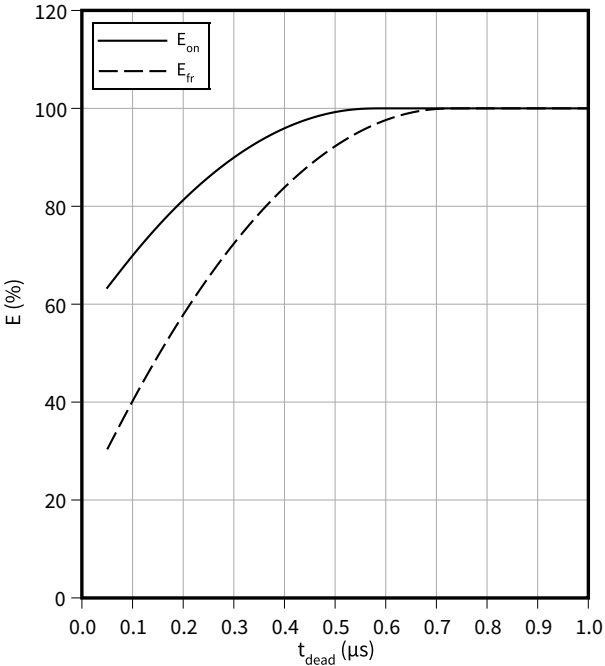
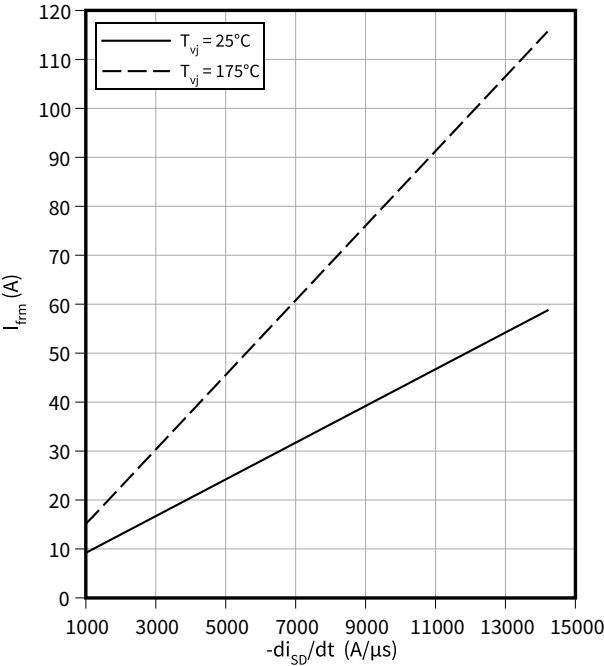
4 Characteristics diagrams

Typical reverse recovery current as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$I_{frm} = f(-di_{SD}/dt)$
 $V_{GS} = 0/18\text{ V}$, $I_{SD} = 32.1\text{ A}$, $V_{DD} = 1000\text{ V}$

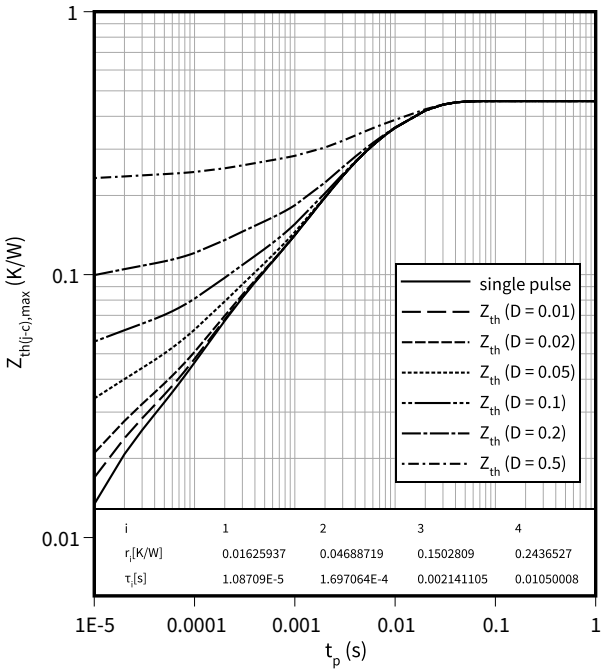
Typical switching energy as a function of dead time / blanking time, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$E = f(t_{dead})$
 $I_D = 32.1\text{ A}$, $T_{vj} = 175\text{ °C}$, $R_{G,ext} = 2.3\text{ }\Omega$, $V_{GS} = 0/18\text{ V}$
 $V_{DD} = 1000\text{ V}$

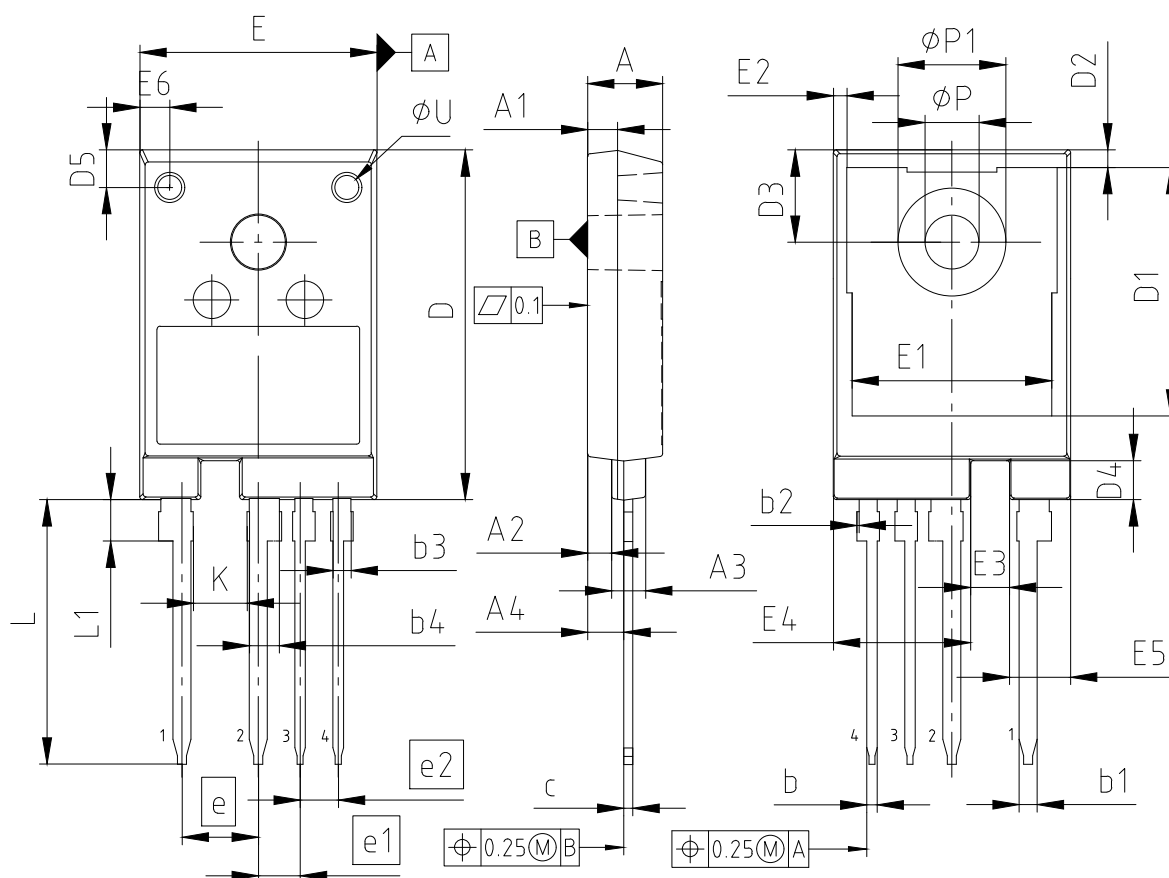


Max. transient thermal impedance (MOSFET/diode)

$Z_{th(j-c),max} = f(t_p)$
 $D = t_p/T$



5 Package outlines



PACKAGE - GROUP NUMBER:		PG-TO247-4-U07			
DIMENSIONS	MILLIMETERS		DIMENSIONS	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	4.90	5.10	E	15.60	16.00
A1	1.90	2.10	E1	13.10	13.50
A2	1.50	1.70	E2	0.60	1.20
A3	2.16	2.36	E3	2.48	2.68
A4	2.31	2.51	E4	9.05	9.25
b	0.60	0.80	E5	3.97	4.17
b1	1.10	1.30	E6	1.80	2.20
b2	---	0.15	e	5.08	
b3	1.10	1.30	e1	2.79	
b4	1.90	2.10	e2	2.54	
c	0.50	0.70	K	3.50	---
D	23.10	23.50	L	17.50	17.80
D1	16.25	16.85	L1	2.61	2.91
D2	0.97	1.37	N	4	
D3	6.00	6.30	ØP1	7.00	7.40
D4	2.50	2.70	ØP	3.50	3.70
D5	2.30	2.70	ØU	1.40	1.80

NOTES: DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS
N IS THE NUMBER OF LEADS

Figure 1

6 Testing conditions

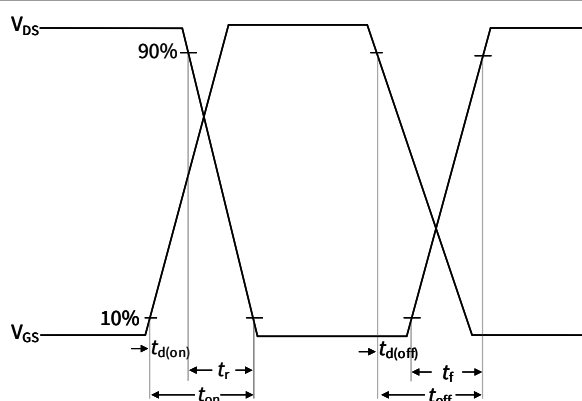


Figure A. Definition of switching times

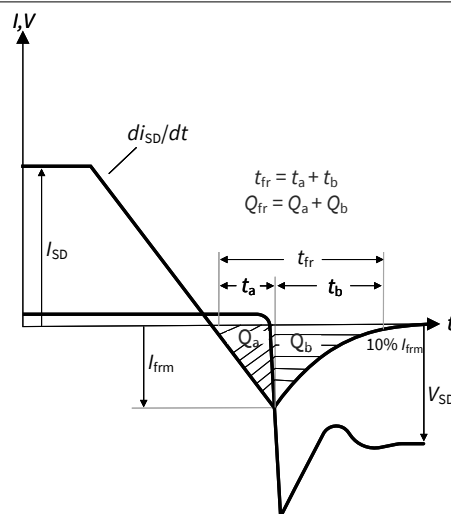


Figure B. Definition of body diode switching characteristics

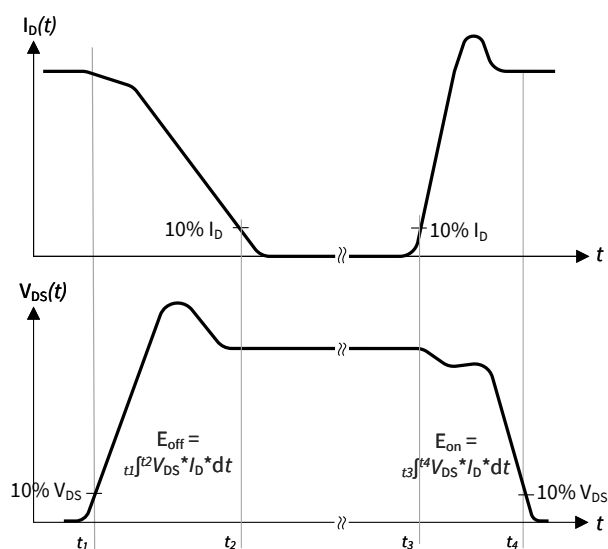


Figure C. Definition of switching losses

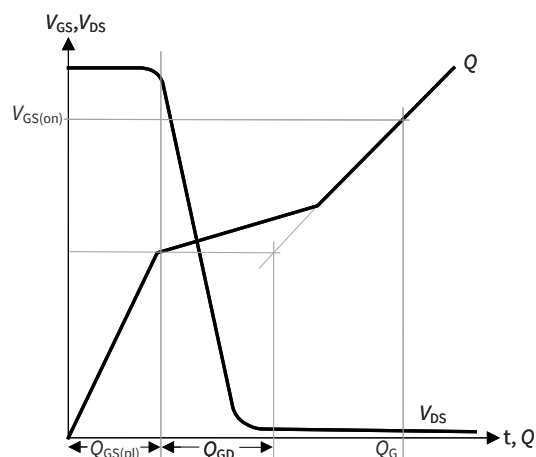


Figure D. Definition of QGD

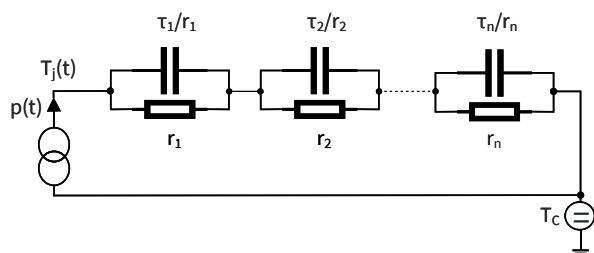


Figure E. Thermal equivalent circuit

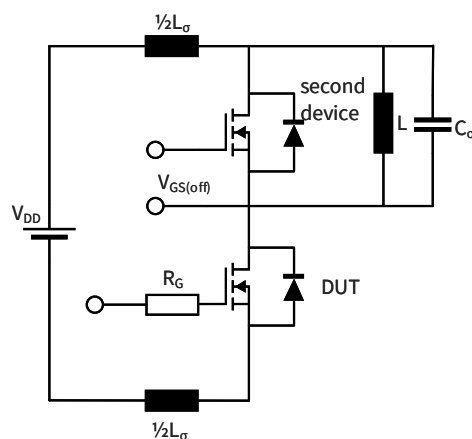


Figure F. Dynamic test circuit

Parasitic inductance L_{σ} ,
Parasitic capacitor C_{σ} ,

Figure 2



Revision history

Revision history

Document revision	Date of release	Description of changes
0.10	2025-05-28	Preliminary datasheet
1.00	2025-06-12	Final datasheet

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